

Title (en)
LEAD-FREE SOLDER ALLOY

Title (de)
BLEIFREIE LÖTLEGIERUNG

Title (fr)
ALLIAGE DE SOUDAGE NE CONTENANT PAS DE PLOMB

Publication
EP 1948388 A1 20080730 (EN)

Application
EP 06794884 A 20061023

Priority
• GB 2006003948 W 20061023
• GB 0521636 A 20051024

Abstract (en)
[origin: GB2431412A] An alloy suitable for use in tinning or the manufacture of heat exchangers, the alloy comprising (by weight): ``1.5 - 6 wt. % copper, ``0.08 - 1.5 wt.% bismuth, ``0 - 1.5 wt.% silver, ``0 - 0.02 wt.% phosphorus, ``0 - 0.02 wt.% germanium, ``0 - 0.15 wt% of indium, ``0 - 0.3 wt% of silicon, ``0 - 0.2 wt% of zirconium, ``one or both of 0.02 - 0.2 wt.% nickel and/or ``0.01 - 0.2 wt.% cobalt, ``and the balance tin, together with unavoidable impurities.

IPC 8 full level
B23K 35/26 (2006.01); **C22C 13/00** (2006.01)

CPC (source: EP GB)
B23K 35/262 (2013.01 - GB); **C22C 13/00** (2013.01 - EP)

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